



GAU 2815
17/11

501.32049R00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yujiro KAJIHARA *et al.*
Serial No.: 09/328,910
Filed: 9 June 1999
For: LEAD FRAME SEMICONDUCTOR INTEGRATED
CIRCUIT DEVICE, USING THE SAME, AND METHOD
OF AND PROCESS FOR FABRICATING THE TWO
Art Unit: 2815
Examiner: J. Clark

TECHNOLOGY CENTER
16/11/01
4-28-01
T. Flowers

AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

9 November 2001

Sir:

In response to the restarted Office Action mailed 11 June 2001 in connection with the above-identified application, the following amendments and remarks are respectfully submitted for entry and consideration.

IN THE SPECIFICATION:

Please replace the paragraph at page 6, lines 31-41 with the following amended paragraph:

--In case the aforementioned individual portions are formed by the pressing, burrs 11 are left on the back of the cut portions. Since the leadframe 1 of the present embodiment is made such that the die pad 3 has a smaller area than that of the semiconductor chip 2 to be mounted thereon, the burrs 11, if any, on the face of the die pad 3 for mounting the semiconductor chip 2 will be unable to mount the chip 2. When the die pad 3 is to be pressed, therefore, it is pressed with its chip

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